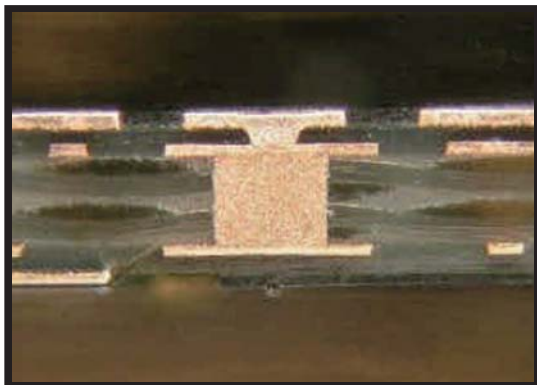
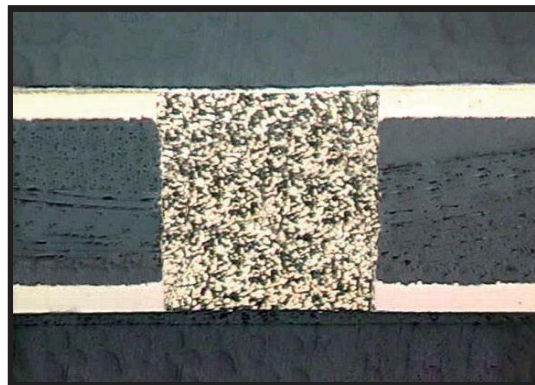


Conductive Copper Paste for Via Filling of Non-Copper Plating Via

DD paste AE2217 / AE1244



1-2-1 Stacked Via type Build-up Core PCB

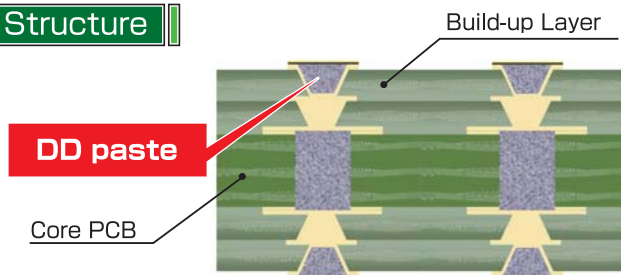


Direct Nickel / Gold plating on AE1244
(Non-copper plating Via)

Features

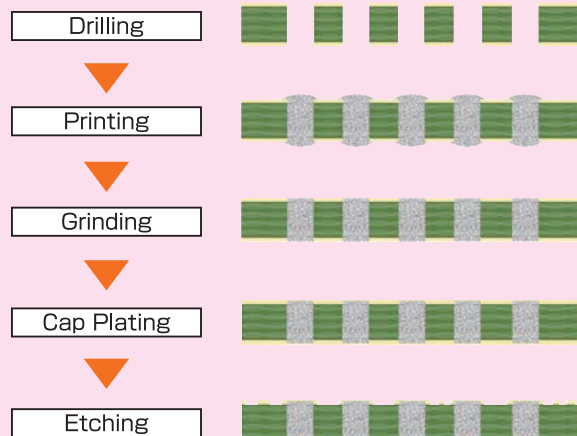
- ▶ Superior conductivity ($4 \times 10^{-5} \Omega \cdot \text{cm}$)
- ▶ Void-less
- ▶ Superior flatness
- ▶ Superior reliability of Cap plating on AE series

Structure



RoHS Compliance

Process



Properties & Characteristics

			Long Life type AE2217	Standard type AE1244
Filler			Silver coating Copper powder	Silver coating Copper powder
Binder			Epoxy resin (2 packed type)	Epoxy resin (1 packed type)
Solvent			Non	Non
Viscosity (BH type)		(Pa·s)	200	110
Curing condition	Pre-heat		80°C/30min	80°C/30min
	Post cure		160°C/60min	160°C/60min
Volume resistivity		($\Omega \cdot \text{cm}$)	$4-5 \times 10^{-5}$	$4-5 \times 10^{-5}$
Glass coefficient (DMA)		($^{\circ}\text{C}$)	113	110
CTE	$\alpha 1$	(ppm)	63	54
	$\alpha 2$	(ppm)	91	103
Thermal conductivity		(W/mK)	13.5	11.7
Peel strength (Non-desmear)		(N/cm)	4.5	4.8

Environmental test

			Long Life type AE2217	Standard type AE1244
Test Items (FR-4, Double-side)			De-lamination&Expansion	De-lamination&Expansion
Normal state			Nothing	Nothing
Solder dip (288°C/10sec/3cycle)			Nothing	Nothing
Thermal cycling (-65°C/30min $\leftrightarrow$ 125°C/30min/1000cycles)			Nothing	Nothing
PCT (121°C/100%RH/2atm/336h)			Nothing	Nothing